

應用田口式方法分析半導體產業製程之最佳組合

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摘要

This paper used the Taguchi method of quality engineering to improve the process quality of nickel-electroplating on the cover-technique of flip chip. For the target of "nominal is best", we investigated the orthogonal array and signal-to-noise ratio to find out the best state of process. Experimental result shows that the Taguchi method can get the best parameter-combinations, and maintain the production-stability.

關鍵字：flip chip, nominal is best, orthogonal array, signal-to-noise ratio